

In the claims:

Please amend the claims as follows:

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Claim 1. (Previously Amended) A method of manufacturing a display device,
comprising:
forming a peeling layer on a first substrate;
forming an insulating layer on said peeling layer;
forming a light emitting element on said insulating layer;
bonding a second substrate over said light emitting element by using a first adhesive;
exposing the peeling layer to a gas containing halogen fluoride after bonding said second
substrate to thereby remove said peeling layer and the first substrate; and
bonding a third substrate to said insulating layer by using a second adhesive.

Claim 2. (Previously Amended) A method according to claim 1, wherein said first
adhesive is selected from the group consisting of polyimide, acrylic, and epoxy resin.

Claim 3. (Previously Amended) A method according to claim 1, wherein the third
substrate comprises the same material as the second substrate.

Claim 4. (Previously Amended) A method of manufacturing a display device,
comprising:
forming a peeling layer on a first substrate;
forming an insulating layer on said peeling layer;
forming a semiconductor element on said insulating layer;
forming at least one interlayer insulating film over the semiconductor element;
forming a light emitting element over the interlayer insulating film, the light emitting
element electrically connected to said semiconductor element;
bonding a second substrate over said light emitting element by using a first adhesive;
exposing the peeling layer to a gas containing halogen fluoride after bonding said second
substrate to thereby remove said peeling layer and first substrate; and

bonding a third substrate to said insulating layer by using a second adhesive.

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Claim 5. (Previously Amended) A method according to claim 4, wherein said first adhesive is selected from the group consisting of polyimide, acrylic, and epoxy resin.

Claim 6. (Previously Amended) A method according to claim 4, wherein the third substrate comprises the same material as the second substrate.

Claims 7-15 (Withdrawn)

Claim 16. (Previously Added) A method according to claim 1, wherein the first substrate is selected from the group consisting of glass, quartz, silicon, metal, and ceramic substrates.

Claim 17. (Previously Added) A method according to claim 1, wherein the second substrate is selected from the group consisting of plastic, glass, quartz, silicon, metal, and ceramic substrates.

Claim 18. (Previously Added) A method according to claim 1, wherein the peeling layer comprises silicon.

Claim 19. (Previously Added) A method according to claim 1, wherein the insulating layer comprises silicon and oxygen.

Claim 20. (Withdrawn)

Claim 21. (Previously Added) A method according to claim 4, wherein the first substrate is selected from the group consisting of glass, quartz, silicon, metal, and ceramic substrates.

Claim 22. (Previously Added) A method according to claim 4, wherein the second substrate is selected from the group consisting of plastic, glass, quartz, silicon, metal, and ceramic substrates.

Claim 23. (Previously Added) A method according to claim 4, wherein the peeling layer comprises silicon.

Claim 24. (Previously Added) A method according to claim 4, wherein the insulating layer comprises silicon and oxygen.

Claim 25. (Withdrawn)

Claim 26. (Currently Amended) A method of manufacturing a display device, comprising:

- forming a peeling layer on a first substrate;
- forming an insulating layer on the peeling layer;
- forming a switching element on the insulating layer;
- forming at least one interlayer insulating film over the switching element;
- forming a display element over the interlayer insulating film, the display element electrically connected to the ~~semiconductor~~ switching element;
- bonding a second substrate over the display element by using a first adhesive;
- exposing the peeling layer to a gas containing halogen fluoride after bonding the second substrate to thereby remove the peeling layer and the first substrate; and
- bonding a third substrate to the insulating layer by using a second adhesive.

Claim 27. (Previously Added) A method according to claim 26, wherein the first substrate is selected from the group consisting of glass, quartz, silicon, metal, and ceramic substrates.

Claim 28. (Previously Added) A method according to claim 26, wherein the second substrate is selected from the group consisting of plastic, glass, quartz, silicon, metal, and ceramic substrates.

Claim 29. (Previously Added) A method according to claim 26, wherein the third substrate comprises the same material as the second substrate.

Claim 30. (Previously Added) A method according to claim 26, wherein said first adhesive is selected from the group consisting of polyimide, acrylic, and epoxy resin.

Claim 31. (Withdrawn)

Claim 32. (Previously Added) A method according to claim 26, wherein the display device is an electroluminescence display device.

Claim 33. (Previously Added) A method according to claim 26, wherein the peeling layer comprises silicon.

Claim 34. (Previously Added) A method according to claim 26, wherein the insulating layer comprises silicon and oxygen.

Claim 35. (Withdrawn)

Currently Amended
Claim 36. (~~Previously Added~~) A method of manufacturing a display device comprising:
forming a peeling layer on a first substrate;
forming an insulating layer on the peeling layer;
forming active layers, a gate insulating layer, and gate electrodes over the insulating layer;
forming a first interlayer insulating layer to cover the gate electrodes;

forming wirings and pixel electrodes over the first interlayer insulating layer, the wirings and the pixel electrodes electrically connected with the active layers, respectively;

exposing the peeling layer to a gas containing halogen fluoride to thereby remove the peeling layer;

forming a light emitting layer and a cathode on at least one of the pixel electrodes electrode;

bonding a second substrate on the cathode by using a first adhesive;

removing the first substrate after bonding the second substrate; and

bonding a third substrate to the insulating layer by using a second adhesive.

Claim 37. (Previously Added) A method according to claim 36, wherein the first substrate is selected from the group consisting of glass, quartz, silicon, metal, and ceramic substrates.

Claim 38. (Previously Added) A method according to claim 36, wherein the second substrate is selected from the group consisting of plastic, glass, quartz, silicon, metal, and ceramic substrates.

Claim 39. (Previously Added) A method according to claim 36, wherein the third substrate comprises the same material as the second substrate.

Claim 40. (Previously Added) A method according to claim 36, wherein said first adhesive is selected from the group consisting of polyimide, acrylic, and epoxy resin.

Claim 41. (Previously Added) A method according to claim 36, wherein the peeling layer comprises silicon.

Claim 42. (Previously Added) A method according to claim 36, wherein the insulating layer comprises silicon and oxygen.

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Claim 43. (Withdrawn)
